

Appl. No. 10/708,277
Amdt. dated May 16, 2006
Reply to Office action of February 08, 2006

Amendments to the Specification:

Please replace paragraph 0029 of the specification with the following amended paragraph:

- 5 Please refer to Fig.8. Fig.8 is a diagram of a displaying frame 100 of the alarming RT-SPC class shown in Fig.3. The displaying frame 100 includes an alarming table 102, which shows the alarming condition of each segment of semiconductor process by manufacturing date. The details of each segment are shown in an alarm list 104, which
- 10 the cause of out-spec according to the lot numbers of the wafers. In addition, users can interactively comment in the alarm list 104. Fig.9 is a diagram of a displaying frame 110 of the RCA class shown in Fig.3. The displaying frame 110 includes a plurality of analysis items 112, ~~an~~analysis an analysis button 114, and a plurality of analysis results 116. Users set the analysis items 112, including manufacturing technology, manufacturing
- 15 product groups, manufacturing products and manufacturing layers. As the analysis button 114 is pushed on, the analysis results 116 are listed by manufacturing variable names, including manufacturing time, the average, the standard deviation, and so on.